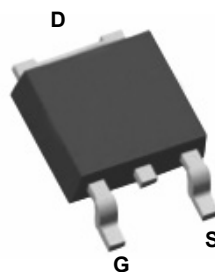
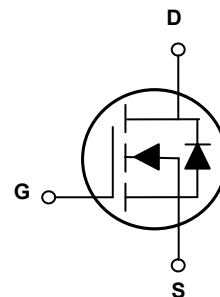


### Main Product Characteristics

$V_{(BR)DSS}$	60V
$R_{DS(ON)}$	28mΩ
$I_D$	27A



TO-252 (DPAK)



Schematic Diagram

### Features and Benefits

- Advanced MOSFET process technology
- Ideal for motor drive, power tools and LED lighting
- Low on-resistance with low gate charge
- Fast switching and reverse body recovery



### Description

The GSFD0625 utilizes the latest techniques to achieve high cell density and low on-resistance. These features make this device extremely efficient and reliable for use in high efficiency switch mode power supply and a wide variety of other applications.

### Absolute Maximum Ratings ( $T_c=25^{\circ}C$ unless otherwise specified)

Parameter	Symbol	Max.	Unit
Drain-Source Voltage	$V_{DS}$	60	V
Gate-Source Voltage	$V_{GS}$	±20	V
Drain Current-Continuous ( $T_c=25^{\circ}C$ )	$I_D$	27	A
Drain Current-Continuous ( $T_c=100^{\circ}C$ )		17	
Drain Current-Pulsed <sup>1</sup>	$I_{DM}$	108	A
Single Pulse Avalanche Energy <sup>2</sup>	$E_{AS}$	26.5	mJ
Single Pulse Avalanche Current <sup>2</sup>	$I_{AS}$	23	A
Power Dissipation ( $T_c=25^{\circ}C$ )	$P_D$	40	W
Power Dissipation-De-rate above 25°C		0.32	
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	62	°C/W
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	3.1	°C/W
Operating Junction Temperature Range	$T_J$	-50 To +150	°C
Storage Temperature Range	$T_{STG}$	-50 To +150	°C

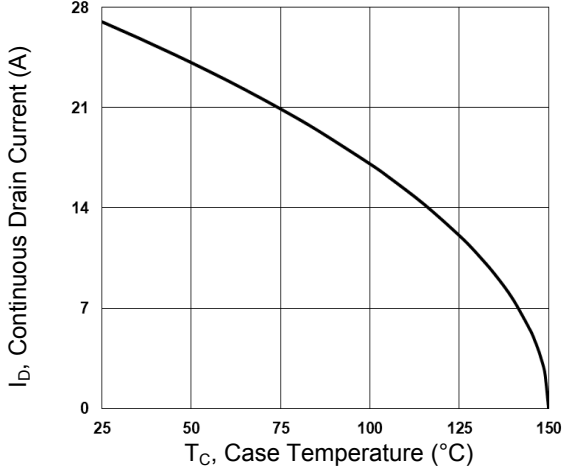
**Electrical Characteristics** ( $T_J=25^{\circ}\text{C}$  unless otherwise specified)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
<b>On/Off Characteristics</b>						
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS}=0V, I_D=250\mu A$	60	-	-	V
$BV_{DSS}$ Temperature Coefficient	$\Delta BV_{DSS}/\Delta T_J$	Reference to $25^{\circ}\text{C}$ , $I_D=1mA$	-	0.06	-	$V/^{\circ}\text{C}$
Drain-Source Leakage Current	$I_{DSS}$	$V_{DS}=60V, V_{GS}=0V,$ $T_J=25^{\circ}\text{C}$	-	-	1	$\mu A$
		$V_{DS}=48V, V_{GS}=0V,$ $T_J=125^{\circ}\text{C}$	-	-	10	$\mu A$
Gate-Source Leakage Current	$I_{GSS}$	$V_{GS}=\pm 20V, V_{DS}=0V$	-	-	$\pm 100$	nA
Static Drain-Source On-Resistance	$R_{DS(ON)}$	$V_{GS}=10V, I_D=15A$	-	23	28	m $\Omega$
		$V_{GS}=4.5V, I_D=10A$	-	27	34	
Gate Threshold Voltage	$V_{GS(th)}$	$V_{GS}=V_{DS}, I_D=250\mu A$	1.2	1.7	2.5	V
$V_{GS(th)}$ Temperature Coefficient	$\Delta V_{GS(th)}$		-	-4.6	-	mV/ $^{\circ}\text{C}$
Forward Transconductance	$g_{fs}$	$V_{DS}=10V, I_D=8A$	-	11	-	S
<b>Dynamic and Switching Characteristics</b>						
Total Gate Charge <sup>3,4</sup>	$Q_g$	$V_{DS}=30V, I_D=10A$ $V_{GS}=10V$	-	16.4	32	nC
Gate-Source Charge <sup>3,4</sup>	$Q_{gs}$		-	3.1	6	
Gate-Drain Charge <sup>3,4</sup>	$Q_{gd}$		-	3.7	7	
Turn-On Delay Time <sup>3,4</sup>	$t_{d(on)}$	$V_{DD}=30V, R_G=6\Omega$ $V_{GS}=10V, I_D=1A$	-	4.6	9	nS
Rise Time <sup>3,4</sup>	$t_r$		-	14.8	28	
Turn-Off Delay Time <sup>3,4</sup>	$t_{d(off)}$		-	27.2	52	
Fall Time <sup>3,4</sup>	$t_f$		-	7.8	15	
Input Capacitance	$C_{iss}$	$V_{DS}=30V, V_{GS}=0V,$ $F=1MHz$	-	1180	2200	pF
Output Capacitance	$C_{oss}$		-	80	160	
Reverse Transfer Capacitance	$C_{rss}$		-	52	100	
Gate Resistance	$R_g$	$V_{GS}=0V, V_{DS}=0V,$ $F=1MHz$	-	1.3	2.6	$\Omega$
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
Continuous Source Current	$I_S$	$V_G=V_D=0V,$ Force Current	-	-	27	A
Pulsed Source Current	$I_{SM}$		-	-	54	A
Diode Forward Voltage	$V_{SD}$	$V_{GS}=0V, I_S=1A,$ $T_J=25^{\circ}\text{C}$	-	-	1	V
Reverse Recovery Time <sup>2</sup>	$t_{rr}$	$V_{GS}=0V, I_S=10A,$ $di/dt=100A/\mu s,$ $T_J=25^{\circ}\text{C}$	-	23	-	nS
Reverse Recovery Charge <sup>2</sup>	$Q_{rr}$		-	13	-	nC

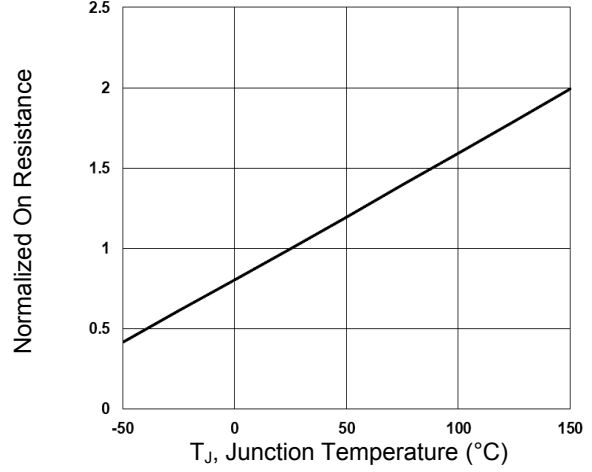
Note:

1. Repetitive rating: Pulsed width limited by maximum junction temperature.
2.  $V_{DD}=50V, V_{GS}=10V, L=0.1mH, I_{AS}=23A, R_G=25\Omega,$  starting  $T_J=25^{\circ}\text{C}$ .
3. Pulse test: pulse width  $\leq 300\mu s,$  duty cycle  $\leq 2\%$ .
4. Essentially independent of operation temperature.

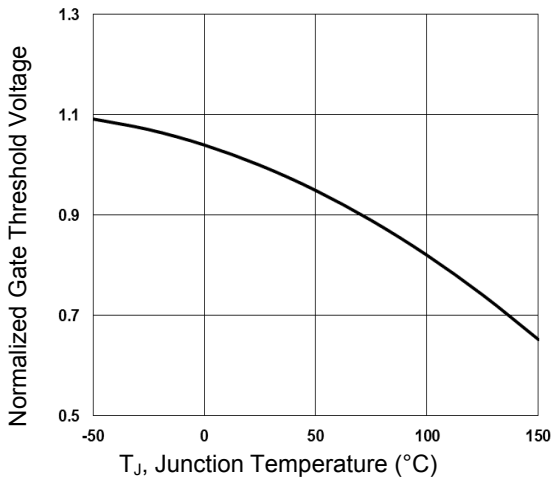
**Typical Electrical and Thermal Characteristic Curves**



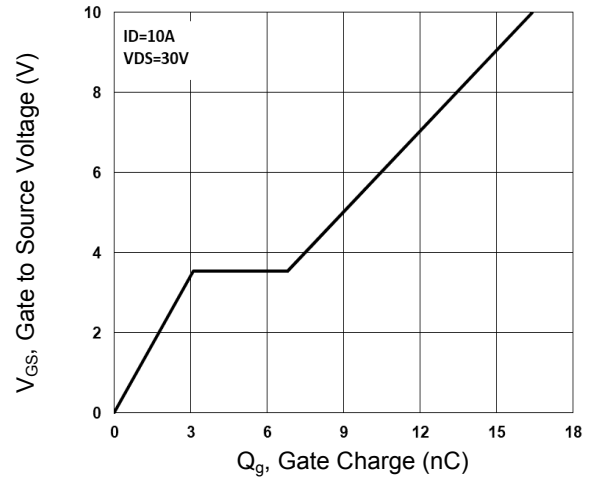
**Figure 1. Continuous Drain Current vs.  $T_C$**



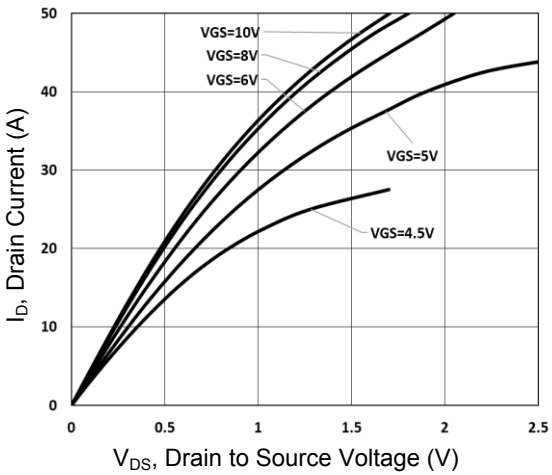
**Figure 2. Normalized  $R_{DS(on)}$  vs.  $T_J$**



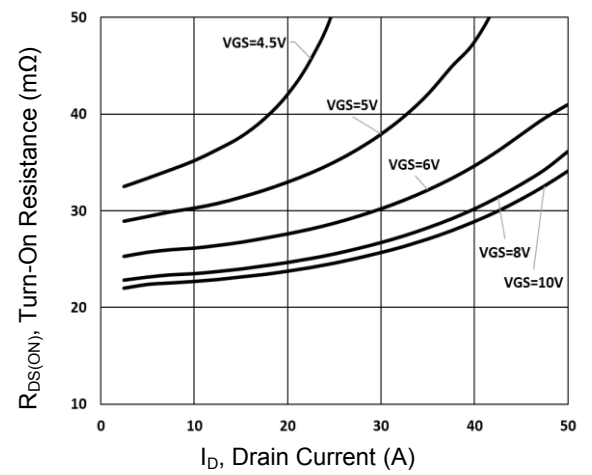
**Figure 3. Normalized  $V_{th}$  vs.  $T_J$**



**Figure 4. Gate Charge Waveform**

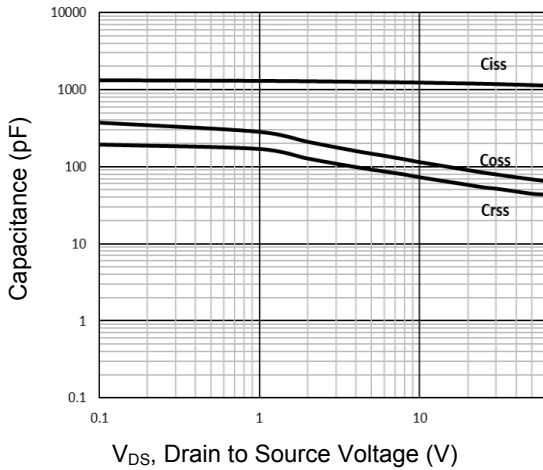


**Figure 5. Typical Output Characteristics**

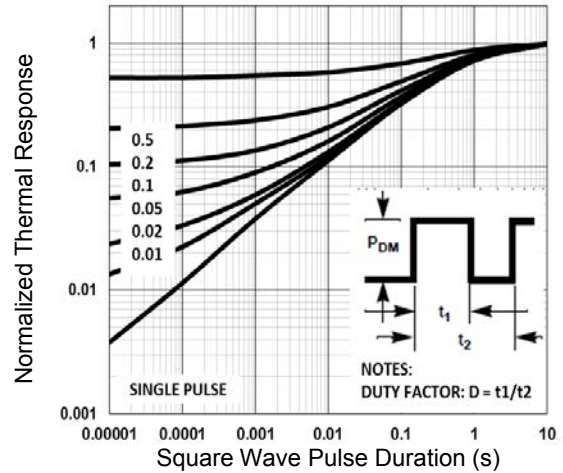


**Figure 6. Turn-on Resistance vs.  $I_D$**

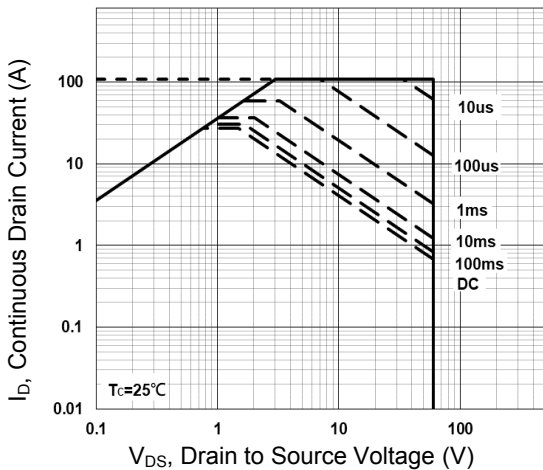
**Typical Electrical and Thermal Characteristic Curves**



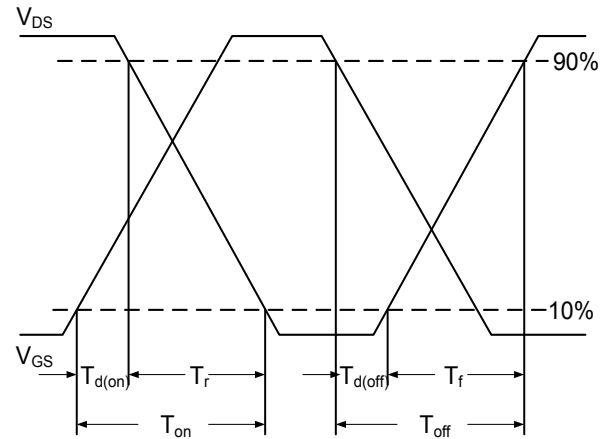
**Figure 7. Capacitance Characteristics**



**Figure 8. Normalized Transient Impedance**

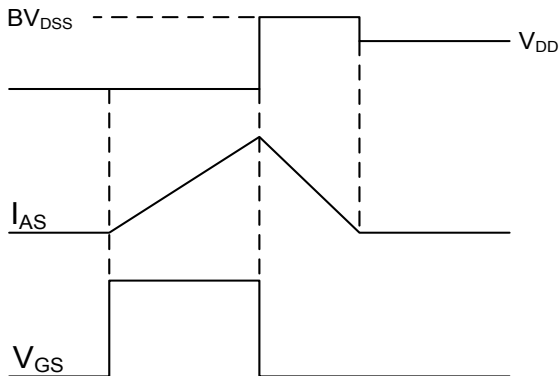


**Figure 9. Maximum Safe Operation Area**



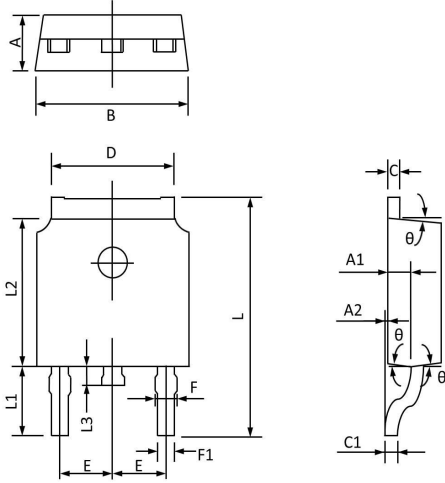
**Figure 10. Switching Time Waveform**

$$E_{AS} = \frac{1}{2} L \times I_{AS}^2 \times \frac{BV_{DSS}}{BV_{DSS} - V_{DD}}$$



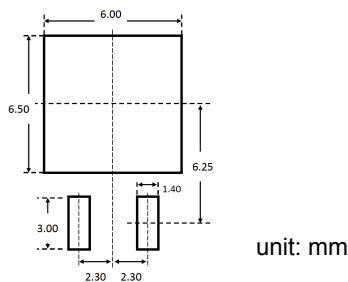
**Figure 11. E<sub>AS</sub> Waveform**

**Package Outline Dimensions TO-252 (DPAK)**



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	2.150	2.450	0.085	0.096
A1	0.910	1.200	0.036	0.047
A2	0.000	0.150	0.000	0.006
B	6.300	6.800	0.248	0.268
C	0.350	0.580	0.014	0.023
C1	0.380	0.550	0.015	0.022
D	5.100	5.500	0.201	0.217
E	2.000	2.390	0.079	0.094
F	0.600	0.940	0.024	0.037
F1	0.500	0.860	0.020	0.034
L	9.400	10.400	0.370	0.409
L1	2.400	3.000	0.094	0.118
L2	5.300	6.200	0.209	0.244
L3	0.600	1.200	0.024	0.047
θ	3°	9°	3°	9°

**Recommended Pad Layout**



**Order Information**

Device	Package	Marking	Carrier	Quantity
GSFD0625	TO-252 (DPAK)	DD6908	Tape & Reel	2,500pcs / Reel